ABSTRACT

WAFER-PROCESSING FILM AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE BY USING WAFER-PROCESSING FILM

A wafer-processing film capable of sufficiently suppressing generation of transfer traces in an adhesive-agent layer when a wafer-processing film having a dicing/die-bonding film composed of the adhesive-agent layer and a bonding film is wound like a roll is provided. A wafer-processing film of the present invention has: a bonding film composed of a base material film and a bonding-agent layer provided on the base material film; and an adhesive-agent layer provided on the bonding-agent layer; wherein the bonding-agent layer contains a radiation polymerizable compound and a first photo initiator in a part corresponding to at least a ring frame and contains the radiation polymerizable compound and a second photo initiator in a part other than a location containing the first photo initiator; and the wavelength of light reactable with the first photo initiator is different from the wavelength of light reactable with the second photo initiator.

Figure 1